

HP8

HOT PLATE



HP8 SOLUTIONS	
	<p>Features and Benefits</p> <ul style="list-style-type: none">+ Up to 200 mm substrates round or 6" square+ Homogeneous temperature distribution+ Fast heating+ High-performance protection coating of hot plate surface+ Easy to use graphical touch screen interface+ Perfectly matches the RCD8 or LabSpin tools:<ul style="list-style-type: none">+ Same footprint+ Same look & feel+ Same reliability+ Programmable heating ramp (with dedicated touch panel controller) <p>Options</p> <ul style="list-style-type: none">+ Various mounting options:<ul style="list-style-type: none">+ Bench Mount (BM)+ TableTop (TT)+ Standalone (T)+ Nitrogen Purge+ Lift pins+ Proximity bake

DEDICATED SOLUTION DESIGNED FOR R&D, LABORATORIES AND SMALL SCALE PRODUCTION+

SUSS MicroTec's manual hot plate HP8 has been developed specifically to meet the requirements of R&D work and small scale production. The 200mm hot plate (HP8) offers homogeneous temperature distribution as well as heating ramps with high repeating accuracy to ensure constant and stable process results.

To aim for best in class temperature distribution SUSS HP8 doesn't rely on conventional heating cartridges. Instead, several meters of heating coils are arranged within the base plate in a process proven pattern. This avoids hot or cool spots and ensures a uniform temperature distribution. The hot plate is specifically coated for increased mechanical and chemical resistance and easy cleaning.

The tool is offered in three different housings (bench mount, table top and stand alone) and can be conveniently controlled through a dedicated touch screen controller. If combined with the coat and develop platform RCD8, the HP8 can be optionally controlled using the same touch screen PC as the RCD8. The table top and bench mount version fits the SUSS MicroTec LabSpin series nicely as well in size and look & feel.

Not only the form factor and control possibilities offer high flexibility, but the variety of available options such as lift pins, proximity bake and nitrogen purge perfectly adapt to the daily lab needs.

The hot plate is equipped with lift pins as a standard, which permits convenient and safe substrate handling. The proximity option allows setting of the distance between substrate and hot

plate surface by a micrometer, thus, giving a broad capability of processing options. The flow rate of the nitrogen purge option can be manually adjusted and is indicated by a digital display. Nitrogen purge and vacuum suction of the substrate can be individually selected for each step in the recipe editor. The closed double walled lid, ensures stable process conditions and prevents accidental touching of the hot surface by the operator.



Display of SUSS HP8

HOT PLATE

The SUSS HP8 is available in three different versions: as a table-top (TT) unit, for integration into a wet bench (BM) or as a stand alone machine.



Bench Mount (BM)

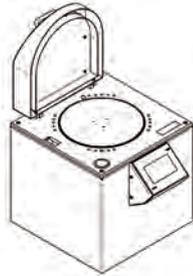
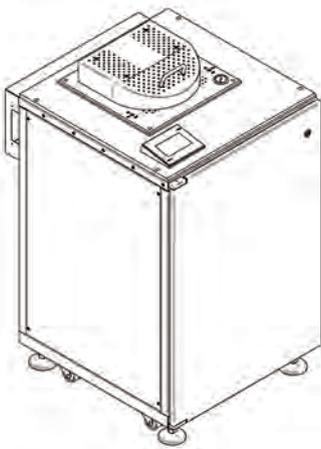


Table Top (TT)



Stand Alone (T)

TOUCH SCREEN CONTROLLER

The dedicated touch screen controller allows convenient editing of the recipes with the capability to choose time, temperature, heating ramps and switched on vacuum or nitrogen purge individually for each step.



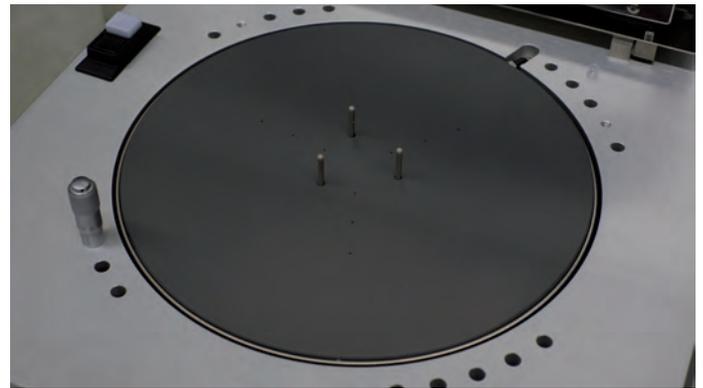
Screenshot of touchscreen panel with intuitive graphical user interface

TECHNICAL DATA

GENERAL

Wafer Size	Up to 200mm round or 6" square
User Interface	Dedicated touch panel controller
# of Recipes	max. 200
# of Steps/Recipe	max. 40
Step Time	0 - 999s in 1 s steps
Optional User Interface	Via controller of SUSS RCD8 tool
# of Recipes	>1000
# of Steps/Recipe	max. 50
Step Time	0 - 999s in 1 s steps
Outputs	Vacuum Nitrogen purge (optional)
Easy Handling	Via 3 lift pins
Temperature	Up to 250°C
Temperature Uniformity	+/-0.5°C up to 120°C +/-1% for 120°C and above
Programmable Heating Ramp	1°C/min up to 10°C/min (with dedicated touch panel controller)
Options	Proximity setting ≥ 0.1 mm Nitrogen purge
Versions	BM, TT, T
Tool Size Dependent on Configuration (w x l x h)	HP8 BM (370 mm x 390 mm x 330 mm) HP8 TT (370 mm x 470 mm x 420 mm) HP8 T (600 mm x 710 mm x 1050 mm)

Data, design and specification depend on individual process conditions and can vary according to equipment configurations. Not all specifications may be valid simultaneously. Illustrations, photos and specifications in this brochure are not legally binding. SUSS MicroTec reserves the right to change machine specifications without prior notice.



Visit www.suss.com/locations for your nearest SUSS representative or contact us:

SÜSS MicroTec AG

Phone: +49 89 32007-0

E-Mail: info@suss.com